

Crystal to LVPECL Clock Generator

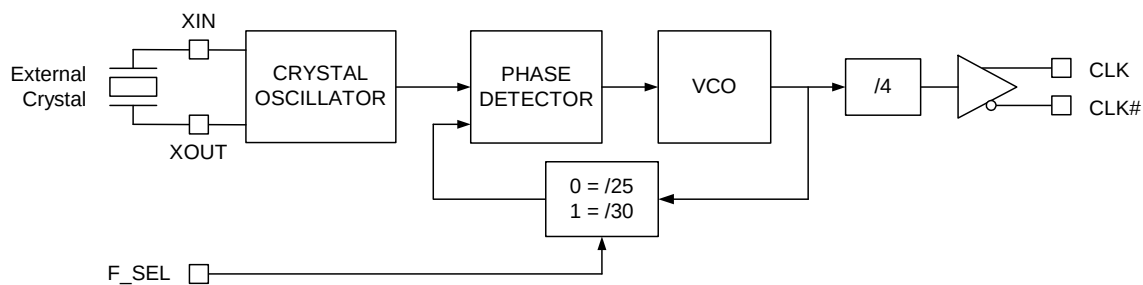
Features

- One LVPECL Output Pair
- Selectable Output Frequency: 156.25 MHz or 187.5 MHz
- External Crystal Frequency: 25 MHz
- Low RMS Phase Jitter at 156.25 MHz, using 25 MHz crystal (1.875 MHz to 20 MHz): 0.33 ps (typical)
- Pb-Free 8-Pin TSSOP Package
- Supply Voltage: 3.3V or 2.5V
- Commercial and Industrial Temperature Ranges

Functional Description

The CY2XP24 is a PLL (Phase Locked Loop) based high performance clock generator. It is optimized to generate 10 Gb Ethernet, Fibre Channel, and other high performance clock frequencies. It produces an output frequency that is either 6.25 times or 7.5 times the crystal frequency. It uses Cypress's low noise VCO technology to achieve low phase jitter, that meets both 10Gb Ethernet, Fibre Channel, and SATA jitter requirements. The CY2XP24 has a crystal oscillator interface input and one LVPECL output pair.

Logic Block Diagram



Pinouts

Figure 1. Pin Diagram - 8 Pin TSSOP



Table 1. Pin Definitions - 8 Pin TSSOP

Pin	Name	Type	Description
1, 8	VDD	Power	3.3V or 2.5V power supply. All supply current flows through pin 1
2	VSS	Power	Ground
3, 4	XOUT, XIN	XTAL Output and Input	Parallel resonant crystal interface
5	F_SEL	CMOS Input	Frequency select. When HIGH, the output frequency is 7.5 times of the crystal frequency. When LOW, the output frequency is 6.25 times of the crystal frequency
6,7	CLK#, CLK	LVPECL Output	Differential clock output

Frequency Table

Inputs		PLL Multiplier Value	Output Frequency (MHz)
Crystal Frequency (MHz)	F_SEL		
25	1	7.5	187.5
25	0	6.25	156.25

Absolute Maximum Conditions

Parameter	Description	Condition	Min	Max	Unit
V _{DD}	Supply Voltage		−0.5	4.4	V
V _{IN} ^[1]	Input Voltage, DC	Relative to V _{SS}	−0.5	V _{DD} + 0.5	V
T _S	Temperature, Storage	Non operating	−65	150	°C
T _J	Temperature, Junction		−	135	°C
ESD _{HBM}	ESD Protection (Human Body Model)	JEDEC STD 22-A114-B	2000	−	V
UL−94	Flammability Rating	At 1/8 in.	V−0		
Θ _{JA} ^[2]	Thermal Resistance, Junction to Ambient	0 m/s airflow	100		°C/W
		1 m/s airflow	91		
		2.5 m/s airflow	87		

Operating Conditions

Parameter	Description	Min	Max	Unit
V _{DD}	3.3V Supply Voltage	3.135	3.465	V
	2.5V Supply Voltage	2.375	2.625	V
T _A	Ambient Temperature, Commercial	0	70	°C
	Ambient Temperature, Industrial	-40	85	°C
T _{PU}	Power up time for all V _{DD} to reach minimum specified voltage (ensure power ramps are monotonic)	0.05	500	ms

DC Electrical Characteristics

Parameter	Description	Test Conditions	Min	Typ	Max	Unit
I _{DD}	Power Supply Current with output unterminated	V _{DD} = 3.465V, F _{OUT} = 187.5 MHz, output unterminated	-	-	125	V
		V _{DD} = 2.625V, F _{OUT} = 187.5 MHz, output unterminated	-	-	120	V
I _{DDT}	Power Supply Current with output terminated	V _{DD} = 3.465V, F _{OUT} = 187.5 MHz, output terminated	-	-	150	V
		V _{DD} = 2.625V, F _{OUT} = 187.5 MHz, output terminated	-	-	145	V
V _{OH}	LVPECL Output High Voltage	V _{DD} = 3.3V or 2.5V, R _{TERM} = 50Ω to V _{DD} - 2.0V	V _{DD} - 1.15	-	V _{DD} - 0.75	V
V _{OL}	LVPECL Output Low Voltage	V _{DD} = 3.3V or 2.5V, R _{TERM} = 50Ω to V _{DD} - 2.0V	V _{DD} - 2.0	-	V _{DD} - 1.625	V

Note

1. The voltage on any input or I/O pin cannot exceed the power pin during power up. Power supply sequencing is NOT required.
2. Simulated using Apache Sentinel TI software. The board is derived from the JEDEC multilayer standard. It measures 76 x 114 x 1.6 mm and has 4-layers of copper (2/1/1/2 oz.). The internal layers are 100% copper planes, while the top and bottom layers have 50% metalization. No vias are included in the model.

DC Electrical Characteristics (continued)

Parameter	Description	Test Conditions	Min	Typ	Max	Unit
V _{OD1}	LVPECL Peak-to-Peak Output Voltage Swing	V _{DD} = 3.3V or 2.5V, R _{TERM} = 50Ω to V _{DD} – 2.0V	600	–	1000	mV
V _{OD2}	LVPECL Output Voltage Swing (V _{OH} – V _{OL})	V _{DD} = 2.5V, R _{TERM} = 50Ω to V _{DD} – 1.5V	500	–	1000	mV
V _{OCM}	LVPECL Output Common Mode Voltage (V _{OH} + V _{OL})/2	V _{DD} = 2.5V, R _{TERM} = 50Ω to V _{DD} – 1.5V	1.2	–	–	V
V _{IH}	Input High Voltage		0.7*V _{DD}	–	V _{DD} + 0.3	V
V _{IL}	Input Low Voltage		–0.3	–	0.3*V _{DD}	V
I _{IH}	Input High Current	F_SEL = V _{DD}	–	–	115	μA
I _{IL}	Input Low Current	F_SEL = V _{SS}	–50	–	–	μA
C _{IN} ^[6]	Input Capacitance, F_SEL		–	15	–	pF
C _{INX} ^[6]	Pin Capacitance, XIN & XOUT		–	4.5	–	pF

AC Electrical Characteristics^[6]

Parameter	Description	Conditions	Min	Typ	Max	Unit
F _{OUT}	Output Frequency		156.25	–	187.5	MHz
T _R , T _F ^[4]	Output Rise/Fall time	20% to 80% of full swing	–	0.5	1.0	ns
T _{Jitter(φ)} ^[7]	RMS Phase Jitter (Random)	156.25 MHz, (1.875–20 MHz), 3.3V	–	0.33	–	ps
		156.25 MHz, (12 kHz –20 MHz), 3.3V	–	0.6	–	ps
T _{DC} ^[8]	Duty Cycle	Measured at zero crossing point	45	–	55	%
T _{LOCK}	Startup Time	Time for CLK to reach valid frequency measured from the time V _{DD} = V _{DD(min.)}	–	–	5	ms
T _{LFS}	Re-lock Time	Time for CLK to reach valid frequency from F_SEL pin change	–	–	1	ms

Recommended Crystal Specifications^[5]

Parameter	Description	Min	Max	Unit
Mode	Mode of Oscillation	Fundamental		
F	Frequency	25	25	MHz
ESR	Equivalent Series Resistance	–	50	Ω
C ₀	Shunt Capacitance	–	7	pF

Notes

3. Outputs are terminated with 50Ω to V_{DD} – 2V. Refer to [Figure 2](#) on page 4 and [Figure 3](#) on page 4.
4. Refer to [Figure 7](#) on page 5.
5. Characterized using an 18 pF parallel resonant crystal.
6. Not 100% tested, guaranteed by design and characterization.
7. Refer to [Figure 4](#) on page 4.
8. Refer to [Figure 7](#) on page 5.

Parameter Measurements

Figure 2. 3.3V Output Load AC Test Circuit

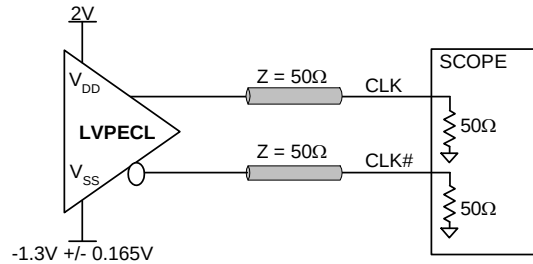


Figure 3. 2.5V Output Load AC Test Circuit

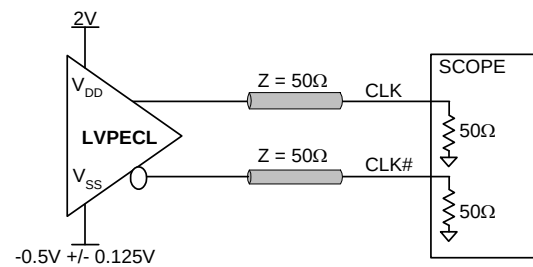


Figure 4. Output DC Parameters

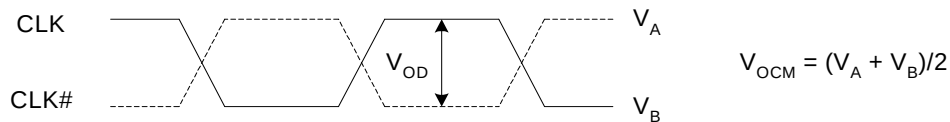


Figure 5. Output Rise and Fall Time

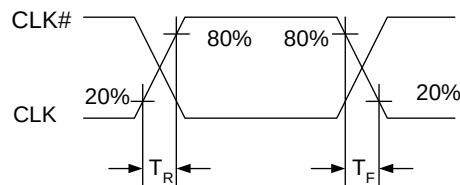


Figure 6. RMS Phase Jitter

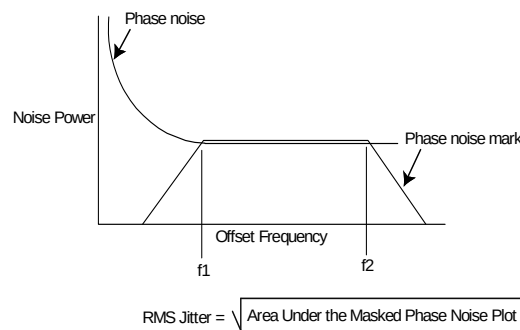
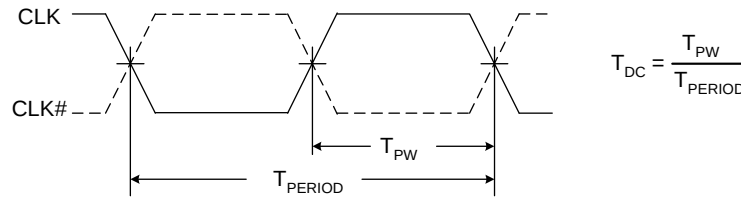


Figure 7. Output Duty Cycle

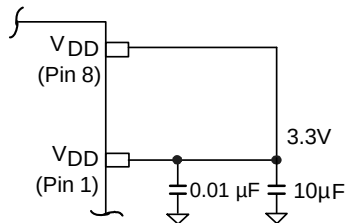


Application Information

Power Supply Filtering Techniques

As in any high speed analog circuitry, noise at the power supply pins can degrade performance. To achieve optimum jitter performance, use good power supply isolation practices. Figure 8 illustrates a typical filtering scheme. Because all current flows through pin 1, the resistance and inductance between this pin and the supply is minimized. A 0.01 or 0.1 μF ceramic chip capacitor is also located close to this pin to provide a short and low impedance AC path to ground. A 1 to 10 μF ceramic or tantalum capacitor is located in the general vicinity of this device and may be shared with other devices.

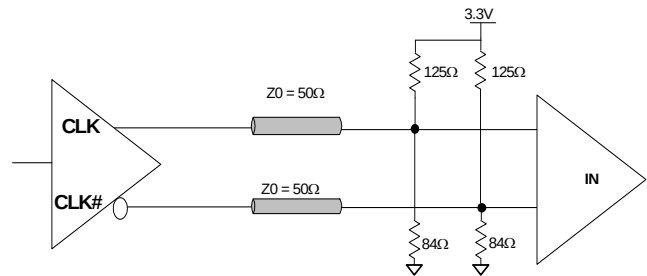
Figure 8. Power Supply Filtering



Termination for LVPECL Output

The CY2XP24 implements its LVPECL driver with a current steering design. For proper operation, it requires a 50 ohm dc termination on each of the two output signals. For 3.3V operation, this data sheet specifies output levels for termination to $V_{DD}-2.0\text{V}$. This termination voltage can also be used for $V_{DD} = 2.5\text{V}$ operation, or it can be terminated to $V_{DD}-1.5\text{V}$. Note that it is also possible to terminate with 50 ohms to ground (V_{SS}), but the high and low signal levels differ from the data sheet values. Termination resistors are best located close to the destination device. To avoid reflections, trace characteristic impedance (Z_0) should match the termination impedance. Figure 9 shows a standard termination scheme.

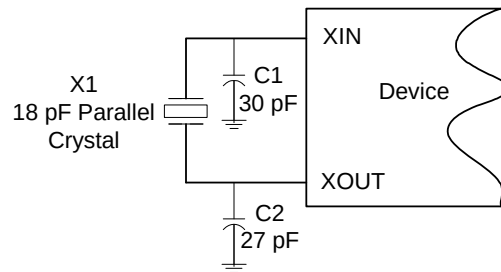
Figure 9. LVPECL Output Termination



Crystal Input Interface

The CY2XP24 is characterized with 18 pF parallel resonant crystals. The capacitor values shown in Figure 10 are determined using a 25 MHz 18 pF parallel resonant crystal and are chosen to minimize the ppm error. Note that the optimal values for C1 and C2 depend on the parasitic trace capacitance and are therefore layout dependent.

Figure 10. Crystal Input Interface

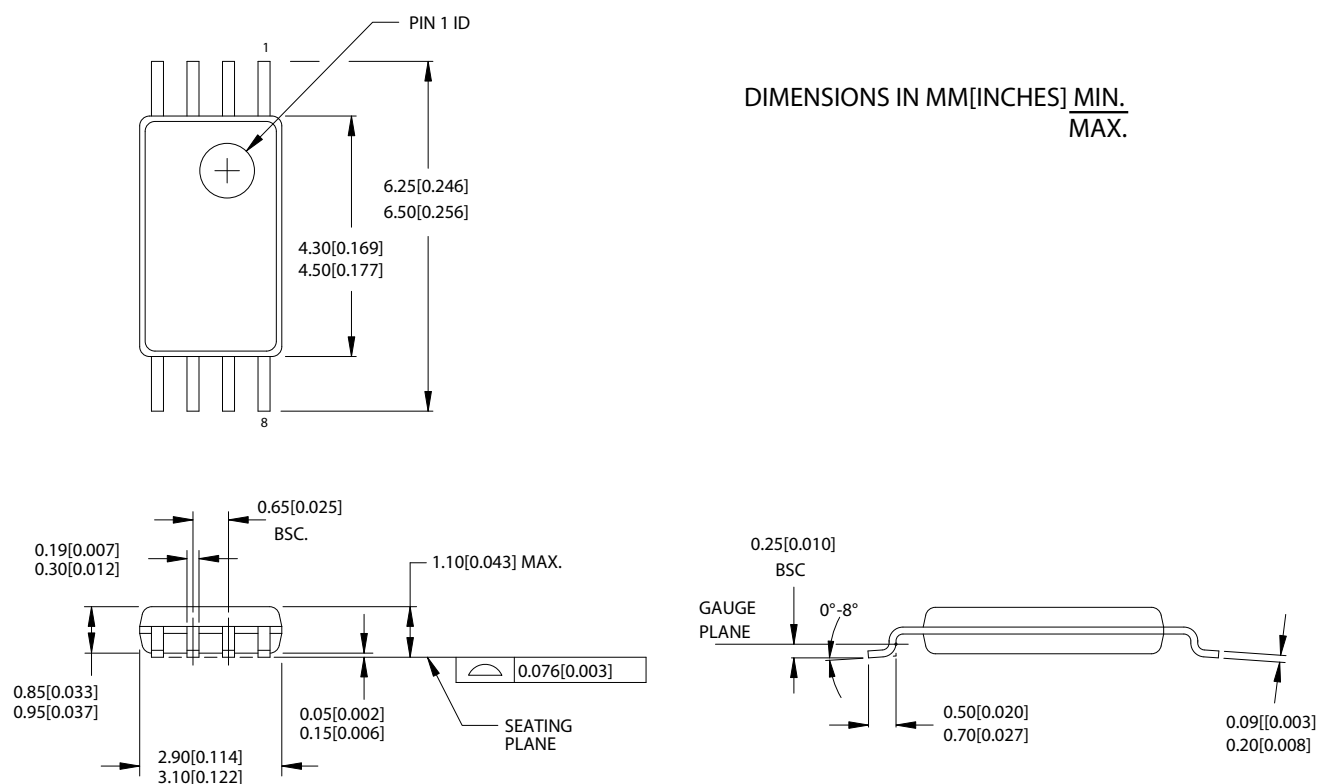


Ordering Information

Part Number	Package Type	Product Flow
CY2XP24ZXC	8-Pin TSSOP	Commercial, 0°C to 70°C
CY2XP24ZXCT	8-Pin TSSOP–Tape and Reel	Commercial, 0°C to 70°C
CY2XP24ZXI	8-Pin TSSOP	Industrial, -40°C to 85°C
CY2XP24ZXIT	8-Pin TSSOP–Tape and Reel	Industrial, -40°C to 85°C

Package Drawing and Dimensions

Figure 11. 8-Pin Thin Shrunk Small Outline Package (4.40 MM Body) Z8



51-85093-*A

Document History Page

Document Title: CY2XP24 Crystal to LVPECL Clock Generator Document Number: 001-15705				
Rev.	ECN No.	Submission Date	Orig. of Change	Description of Change
**	1285703	See ECN	WWZ/KVM/ARI	New data sheet
*A	1451704	See ECN	WWZ/AESA	Added I-temp devices
*B	2669117	03/05/2009	KVM/AESA	Changed crystal frequency and output frequencies Updated phase jitter value Rise & fall times changed from 350 ps to 500 ps (typ.) Junction temperature changed from 125°C to 135°C Changed IIL and IIH values Entered value for IDD Removed MSL spec Changed Data Sheet Status to Final
*C	2700242	04/30/2009	KVM/PYRS	Typos: changed VCC to VDD, changed ps to MHz Changed footnote about external power dissipation Reformatted AC and DC tables Changed LVPECL parameters from VPP to VOD and VOCM Added CINX spec Added IDD for 2.5V Added TLOCK timing Revised text in Application Information section Changed recommended crystal load capacitor values
*D	2718433	06/12/2009	WWZ/HMT	No change. Submit to ECN for product launch.
*E	2767308	09/22/2009	KVM	Add phase jitter spec for 12 kHz - 20 MHz integration range Add I_{DD} spec for unterminated outputs Change parameter name for I_{DD} (terminated outputs) from I_{DD} to I_{DDT} Remove I_{DD} footnote about externally dissipated current Add footnote reference to C_{IN} and C_{INX} : not 100% tested Add max limit for T_R , T_F : 1.0 ns Change T_{LOCK} max from 10 ms to 5 ms Split out parameter T_{LFS} from T_{LOCK}

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